

# Ahmed Sharif

## List of Publications by Year in descending order

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62  
papers

1,680  
citations

257357

24  
h-index

289141

40  
g-index

73  
all docs

73  
docs citations

73  
times ranked

994  
citing authors

#	ARTICLE	IF	CITATIONS
1	Study on wear properties of aluminium-silicon piston alloy. Journal of Materials Processing Technology, 2001, 118, 69-73.	3.1	129
2	Effect of volume in interfacial reaction between eutectic Sn-3.5% Ag-0.5% Cu solder and Cu metallization in microelectronic packaging. Journal of Electronic Materials, 2005, 34, 143-149.	1.0	88
3	Effect of indium addition in Sn-rich solder on the dissolution of Cu metallization. Journal of Alloys and Compounds, 2005, 390, 67-73.	2.8	76
4	The influence of addition of Al nano-particles on the microstructure and shear strength of eutectic Sn-Ag-Cu solder on Au/Ni metallized Cu pads. Journal of Alloys and Compounds, 2010, 506, 216-223.	2.8	76
5	Transient liquid phase Ag-based solder technology for high-temperature packaging applications. Journal of Alloys and Compounds, 2014, 587, 365-368.	2.8	72
6	Dissolution kinetics of BGA Sn-Pb and Sn-Ag solders with Cu substrates during reflow. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2004, 106, 126-131.	1.7	66
7	Influence of SrTiO <sub>3</sub> nano-particles on the microstructure and shear strength of Sn-Ag-Cu solder on Au/Ni metallized Cu pads. Journal of Alloys and Compounds, 2011, 509, 1885-1892.	2.8	66
8	Influence of small amount of Al and Cu on the microstructure, microhardness and tensile properties of Sn-Zn binary eutectic solder alloy. Journal of Alloys and Compounds, 2009, 481, 167-172.	2.8	61
9	Effect of micron size Ni particle addition in Sn-8Zn-3Bi lead-free solder alloy on the microstructure, thermal and mechanical properties. Journal of Alloys and Compounds, 2014, 585, 32-39.	2.8	59
10	Comparative study of the dissolution kinetics of electrolytic Ni and electroless Ni-P by the molten Sn <sub>3.5</sub> Ag <sub>0.5</sub> Cu solder alloy. Microelectronics Reliability, 2003, 43, 2031-2037.	0.9	57
11	Effect of volume in interfacial reaction between eutectic Sn-Pb solder and Cu metallization in microelectronic packaging. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2004, 106, 120-125.	1.7	57
12	Dissolution of electroless Ni metallization by lead-free solder alloys. Journal of Alloys and Compounds, 2005, 388, 75-82.	2.8	48
13	Interfacial reactions of BGA Sn-3.5%Ag-0.5%Cu and Sn-3.5%Ag solders during high-temperature aging with Ni/Au metallization. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2004, 113, 184-189.	1.7	46
14	Influence of Ag micro-particle additions on the microstructure, hardness and tensile properties of Sn-Zn binary eutectic solder alloy. Microelectronics Reliability, 2010, 50, 1134-1141.	0.9	46
15	Evidence of superparamagnetism and improved electrical properties in Ba and Ta co-doped BiFeO <sub>3</sub> ceramics. Journal of Alloys and Compounds, 2018, 735, 2584-2596.	2.8	46
16	Interfacial microstructure and shear strength of Ag nano particle doped Sn-Zn solder in ball grid array packages. Microelectronics Reliability, 2009, 49, 746-753.	0.9	42
17	The effect of curing on the performance of ACF bonded chip-on-flex assemblies after thermal ageing. Soldering and Surface Mount Technology, 2005, 17, 40-48.	0.9	40
18	Effect of substrate metallization on interfacial reactions and reliability of Sn-Zn-Bi solder joints. Microelectronic Engineering, 2007, 84, 328-335.	1.1	40

#	ARTICLE	IF	CITATIONS
19	Effect of nano Al <sub>2</sub> O <sub>3</sub> additions on the microstructure, hardness and shear strength of eutectic Sn-9Zn solder on Au/Ni metallized Cu pads. <i>Microelectronics Reliability</i> , 2010, 50, 2051-2058.	0.9	36
20	Correlation of charge defects and morphology with magnetic and electrical properties of Sr and Ta codoped BiFeO <sub>3</sub> . <i>Journal of Alloys and Compounds</i> , 2016, 688, 1186-1194.	2.8	35
21	Investigation of small Sn-3.5Ag-0.5Cu additions on the microstructure and properties of Sn-8Zn-3Bi solder on Au/Ni/Cu pads. <i>Journal of Alloys and Compounds</i> , 2010, 489, 678-684.	2.8	32
22	Effect of 9wt.% in addition to Sn-3.5Ag-0.5Cu solder on the interfacial reaction with the Au/NiP metallization on Cu pads. <i>Journal of Alloys and Compounds</i> , 2005, 396, 217-223.	2.8	31
23	Liquid and solid state interfacial reactions of Sn-Ag-Cu and Sn-In-Ag-Cu solders with Ni-P under bump metallization. <i>Thin Solid Films</i> , 2006, 504, 431-435.	0.8	30
24	Effect of small Sn-3.5Ag-0.5Cu additions on the structure and properties of Sn-9Zn solder in ball grid array packages. <i>Microelectronic Engineering</i> , 2009, 86, 2347-2353.	1.1	29
25	Investigation of interfacial reactions between Sn-Zn solder with electrolytic Ni and electroless Ni(P) metallization. <i>Journal of Alloys and Compounds</i> , 2007, 440, 117-121.	2.8	24
26	Interfacial reactions on electrolytic Ni and electroless Ni(P) metallization with Sn-In-Ag-Cu solder. <i>Journal of Alloys and Compounds</i> , 2005, 393, 135-140.	2.8	23
27	Comparative study of interfacial reactions of Sn-Ag-Cu and Sn-Ag solders on Cu pads during reflow soldering. <i>Journal of Electronic Materials</i> , 2005, 34, 46-52.	1.0	22
28	Effects of transition metal (Fe, Co & Ni) doping on structural, electronic and optical properties of CuO: DFT+U study. <i>Chemical Physics</i> , 2021, 545, 111160.	0.9	21
29	Interfacial reactions of Sn-Cu and Sn-Pb-Ag solder with Au/Ni during extended time reflow in ball grid array packages. <i>Journal of Materials Research</i> , 2004, 19, 2897-2904.	1.2	19
30	Effect of Ag micro-particles content on the mechanical strength of the interface formed between Sn-Zn binary solder and Au/Ni/Cu bond pads. <i>Microelectronic Engineering</i> , 2009, 86, 2086-2093.	1.1	19
31	Structural transition and its effect in La, Zr co-substituted mono-domain BiFeO <sub>3</sub> . <i>Journal of Applied Physics</i> , 2016, 120, 214106.	1.1	19
32	Retardation of spalling by the addition of Ag in Sn-Zn-Bi solder with the Au/Ni metallization. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2007, 445-446, 686-690.	2.6	18
33	Customized glass sealant for ceramic substrates for high temperature electronic application. <i>Microelectronics Reliability</i> , 2014, 54, 2905-2910.	0.9	18
34	Structural, dielectric and magnetic properties of Ta-substituted Bi <sub>0.8</sub> La <sub>0.2</sub> FeO <sub>3</sub> multiferroics. <i>Journal of Alloys and Compounds</i> , 2015, 622, 471-476.	2.8	16
35	Interfacial reactions of Sn-3.5% Ag and Sn-3.5% Ag-0.5% Cu solder with electroless Ni/Au metallization during multiple reflow cycles. <i>Journal of Materials Science: Materials in Electronics</i> , 2005, 16, 153-158.	1.1	14
36	Study of off-eutectic Zn-xMg high temperature solder alloys. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 8734-8744.	1.1	14

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37	Nanocharacterization of interface between natural fiber and polymer matrix: an overview. <i>Composite Interfaces</i> , 2016, 23, 105-123.	1.3	14
38	Effect of reaction time on mechanical strength of the interface formed between the Sn-Zn(-Bi) solder and the Au/Ni/Cu bond pad. <i>Journal of Electronic Materials</i> , 2006, 35, 1812-1817.	1.0	13
39	Study on the properties of Zn $\epsilon$ -xNi high temperature solder alloys. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 3608-3618.	1.1	13
40	Enhanced dielectric stability and coercivity of band gap tuned Ba $\epsilon$ -Al Co-doped bismuth ferrite: An experimental and DFT+U investigation. <i>Ceramics International</i> , 2022, 48, 3404-3416.	2.3	12
41	Pb-Free Glass Paste: A Metallization-Free Die-Attachment Solution for High-Temperature Application on Ceramic Substrates. <i>Journal of Electronic Materials</i> , 2013, 42, 2667-2676.	1.0	11
42	ZnSxSe1 $\hat{~}$ x nanowire arrays with tunable optical properties grown on ZnS nanoribbon substrates. <i>Physica E: Low-Dimensional Systems and Nanostructures</i> , 2009, 41, 739-745.	1.3	10
43	Review on advances in nanoscale microscopy in cement research. <i>Micron</i> , 2016, 80, 45-58.	1.1	10
44	Characteristics of eutectic and near-eutectic Zn $\epsilon$ -Al alloys as high-temperature lead-free solders. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 1691-1702.	1.1	9
45	Synthesis and characterization of indium doped cadmium sulfide nanoribbons. <i>Journal Physics D: Applied Physics</i> , 2009, 42, 035412.	1.3	6
46	Effect of Areca and Waste Nylon Fiber Hybridization on the Properties of Recycled Polypropylene Composites. <i>Journal of Natural Fibers</i> , 2022, 19, 6625-6637.	1.7	6
47	Comparative Study of the Dissolution Kinetics of Electrolytic Ni and Electroless NiP Layers by Molten Sn3.5Ag Solder Alloy. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , 2005, 127, 365-369.	1.2	4
48	Characteristics of Zn $\epsilon$ -Sb based high temperature solder alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 18417-18425.	1.1	4
49	Effect of nano Ni additions on the structure and properties of Sn-9Zn and Sn-8Sn-3Bi solder in ball grid array packages. , 2008, , .		3
50	Utilization of open pit burned household waste ash $\hat{\epsilon}$ a feasibility study in Dhaka. <i>Waste Management and Research</i> , 2014, 32, 397-405.	2.2	3
51	Zn-Based Solders for High Temperature Electronic Application. , 2016, , .		3
52	Study of thin film metallization adhesion in ceramic multichip module. , 2012, , .		2
53	Mechanical and Thermal Properties of Zn-xMg Solder Alloys. <i>Applied Mechanics and Materials</i> , 2016, 860, 173-178.	0.2	2
54	Effect of Minor Addition of Ni on the Microstructure and Properties of Zn-Based High-Temperature Solder. <i>Journal of Electronic Materials</i> , 2020, 49, 3990-4001.	1.0	2

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55	Role of hydrogen co-doping on opto-electronic behaviors of Na-H co-doped zinc oxide: a first principle study. Journal of Physics Communications, 2020, 4, 115002.	0.5	2
56	Effect of multiple reflows on mechanical strength of the interface formed between Sn <sup>62</sup> Zn <sup>62</sup> Bi solder and Au/Ni/Cu bond pad. Journal of Materials Research, 2007, 22, 40-45.	1.2	1
57	Effect of 3 wt.% Bi in Sn-Zn solder on the interfacial reaction with the Au/Ni metallization in microelectronic packaging. , 2008, , .		1
58	Ceramic &#x2014; Ceramic joining using glass frit for high temperature application. , 2012, , .		1
59	Effect of 3 wt.% Bi in Sn-Zn solder on the interfacial reactions with the Au/Ni metallization. Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International, 2006, , .	0.0	0
60	A study of Ag micro-particle reinforced Sn-Zn matrix composite solder. , 2008, , .		0
61	Effect of small Sn-Ag-Cu additions on structure and properties of Sn-Zn-Bi solder/BGA during as-soldered and as-aged conditions. , 2009, , .		0
62	Electronic packages for high pressure applications: A dome-shaped cavity design. , 2013, , .		0